

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

Brightking's SET23A12L02-E18 is designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD), electrical fast transients (EFT) and lightning. TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components. The low profile SOT-23 package allows flexibility in the design of crowded circuit boards.

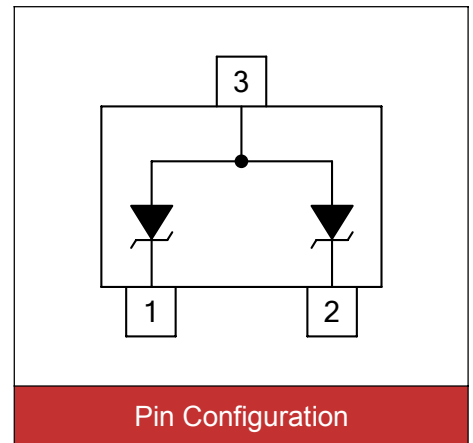


Contact: $\pm 30\text{kV}$
Air: $\pm 30\text{kV}$



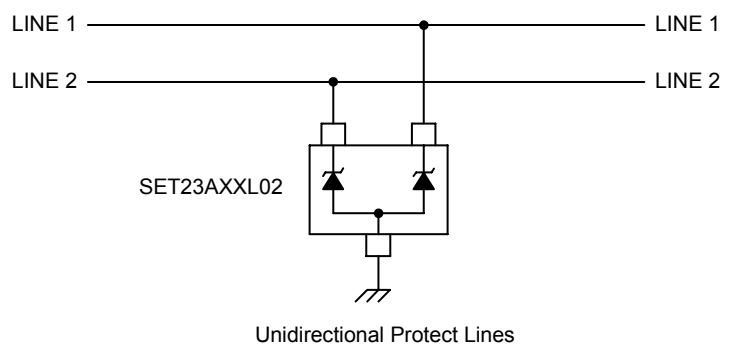
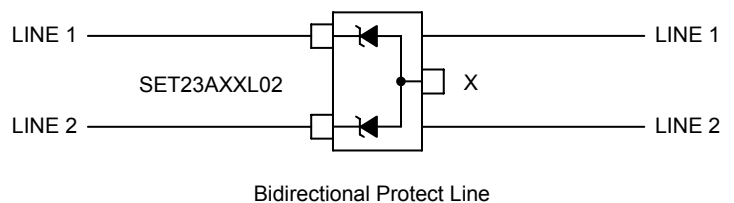
Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOT-23 surface mount package
- Protects one bidirectional line or two unidirectional lines
- Working voltage: 12V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: B 12C
- Weight: 0.008g



Applications

- Cellular handsets and accessories
- Personal digital assistants (PDA's)
- Portable instrumentation
- Set Top Box (STB)
- Servers, notebook, and desktop PC
- Wireless bus protection
- RS-232, RS-422, RS-423 protection



Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse power (tp=8/20μs waveform)	P _{PP}	500	W
ESD voltage (Contact discharge)	V _{ESD}	±30	kV
ESD voltage (Air discharge)		±30	
Storage & operating temperature range	T _{STG} , T _J	-55~+150	°C

Electrical Characteristics (T_J=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V _{RWM}				12	V
Reverse breakdown voltage	V _{BR}	I _{BR} =1mA	13.3			V
Reverse leakage current	I _R	V _R =12V Each I/O pin			1	μA
Clamping voltage (tp=8/20μs)	V _C	I _{PP} =1A			19	V
Clamping voltage (tp=8/20μs)	V _C	I _{PP} =18A			27	V
Off state junction capacitance	C _J	0Vdc, f=1MHz Between I/O pins and GND		100		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

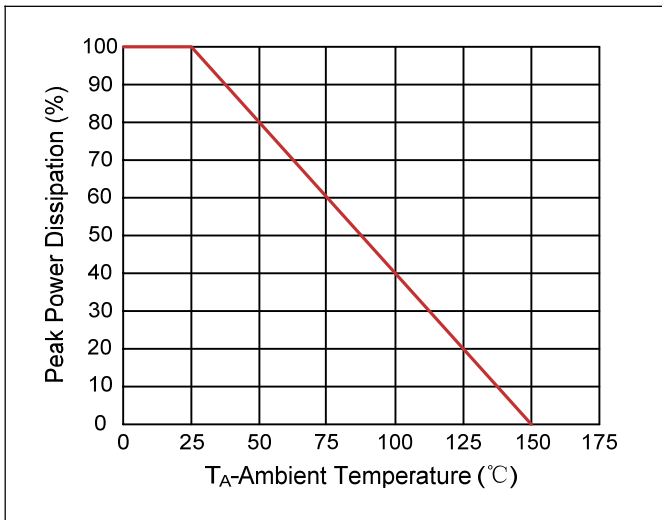


Figure 2. Pulse Waveforms

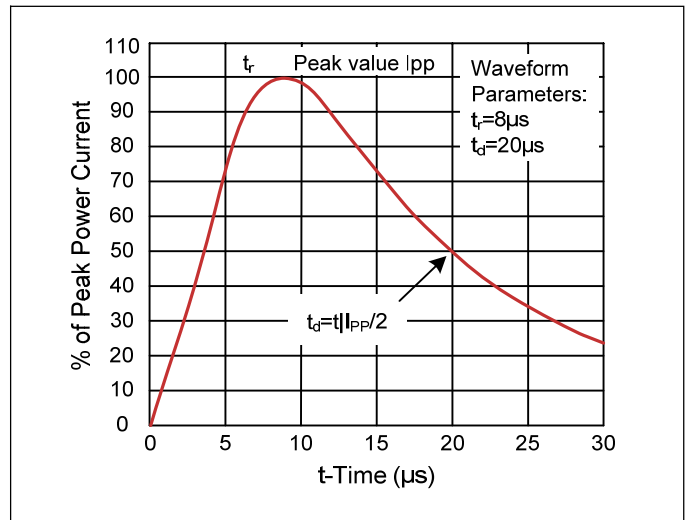


Figure 3. Forward Voltage vs. Forward Current

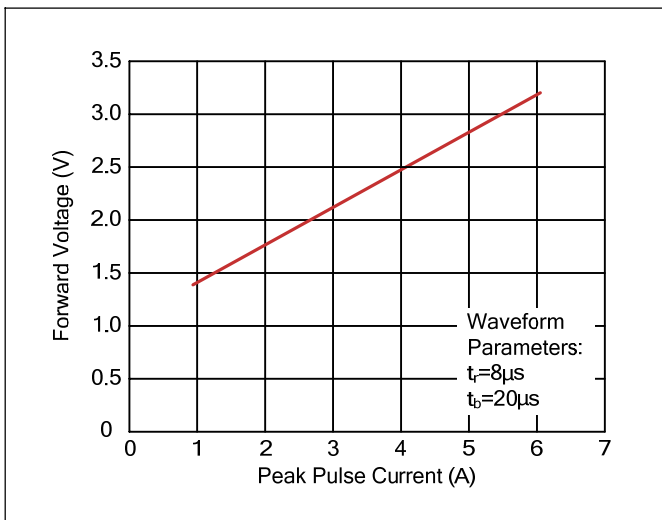
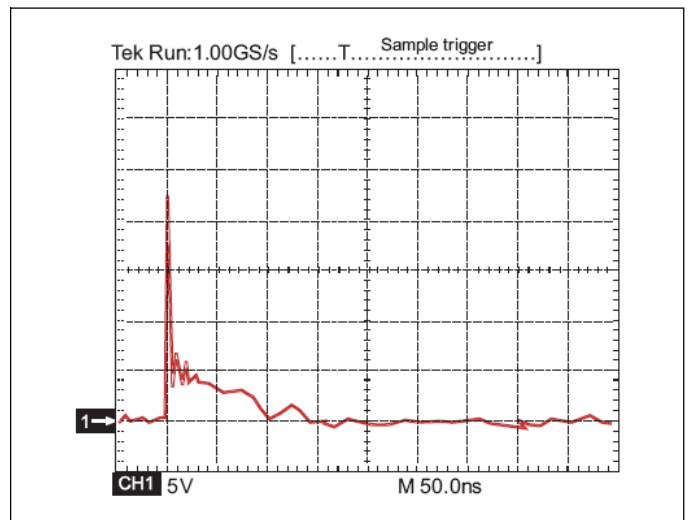
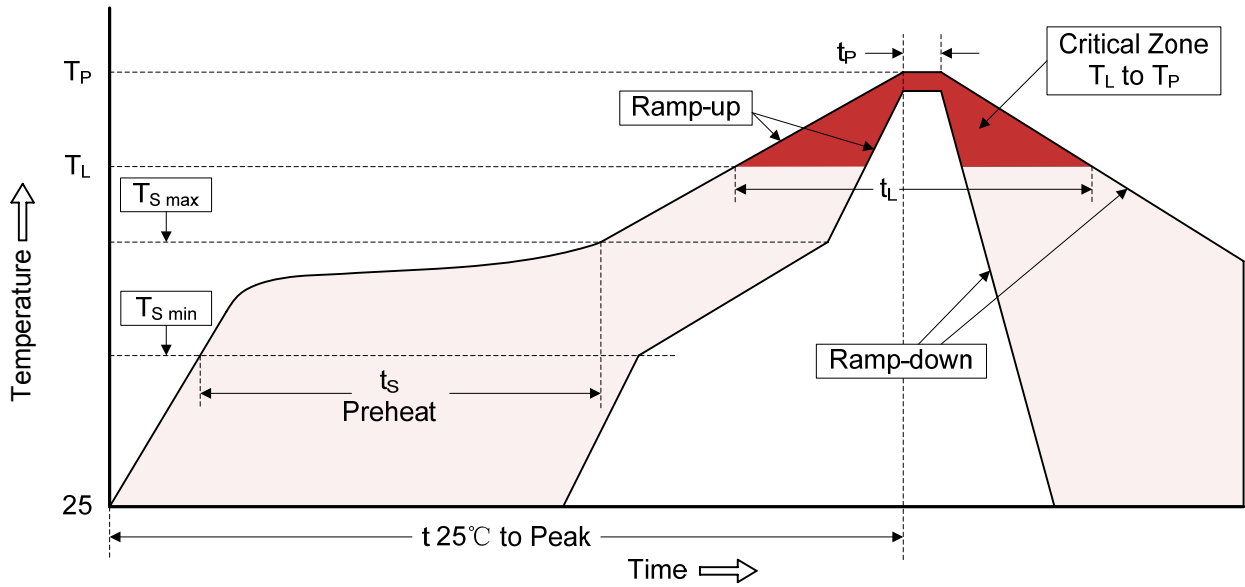


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

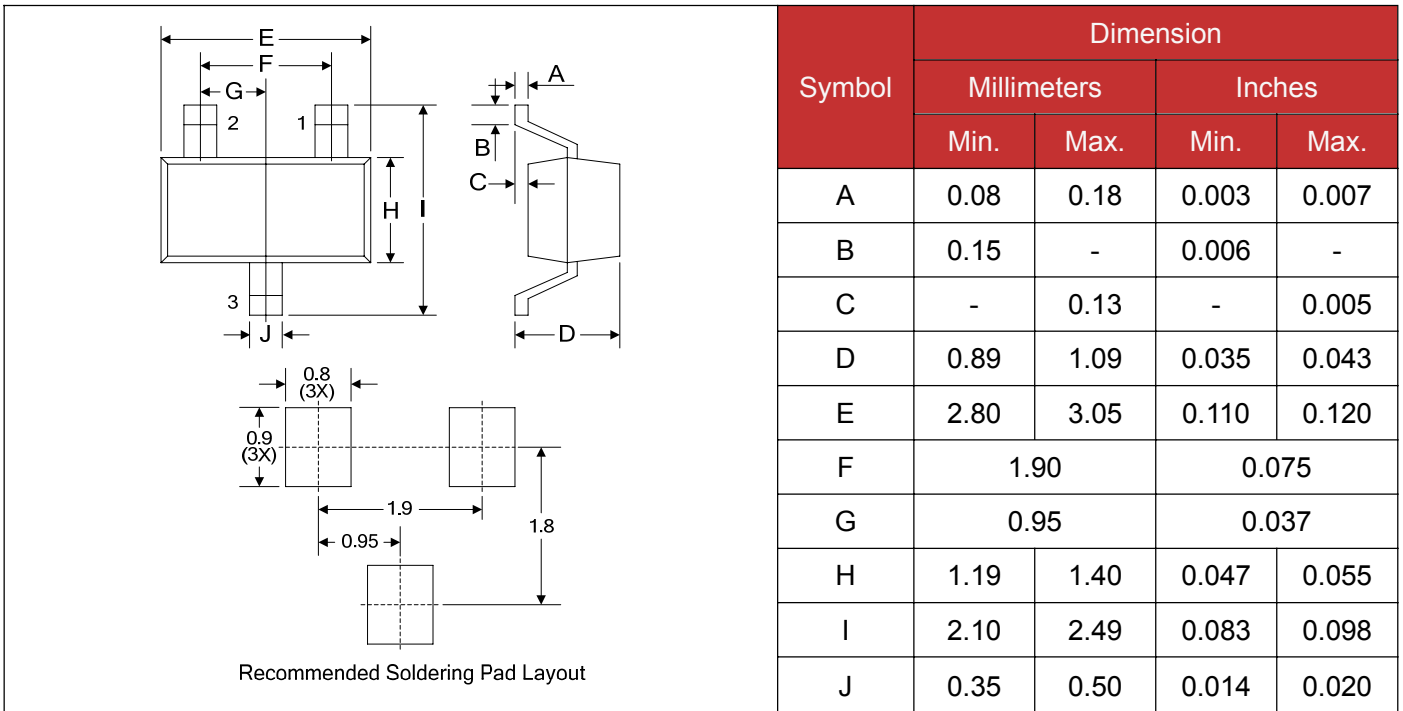
Reflow Soldering



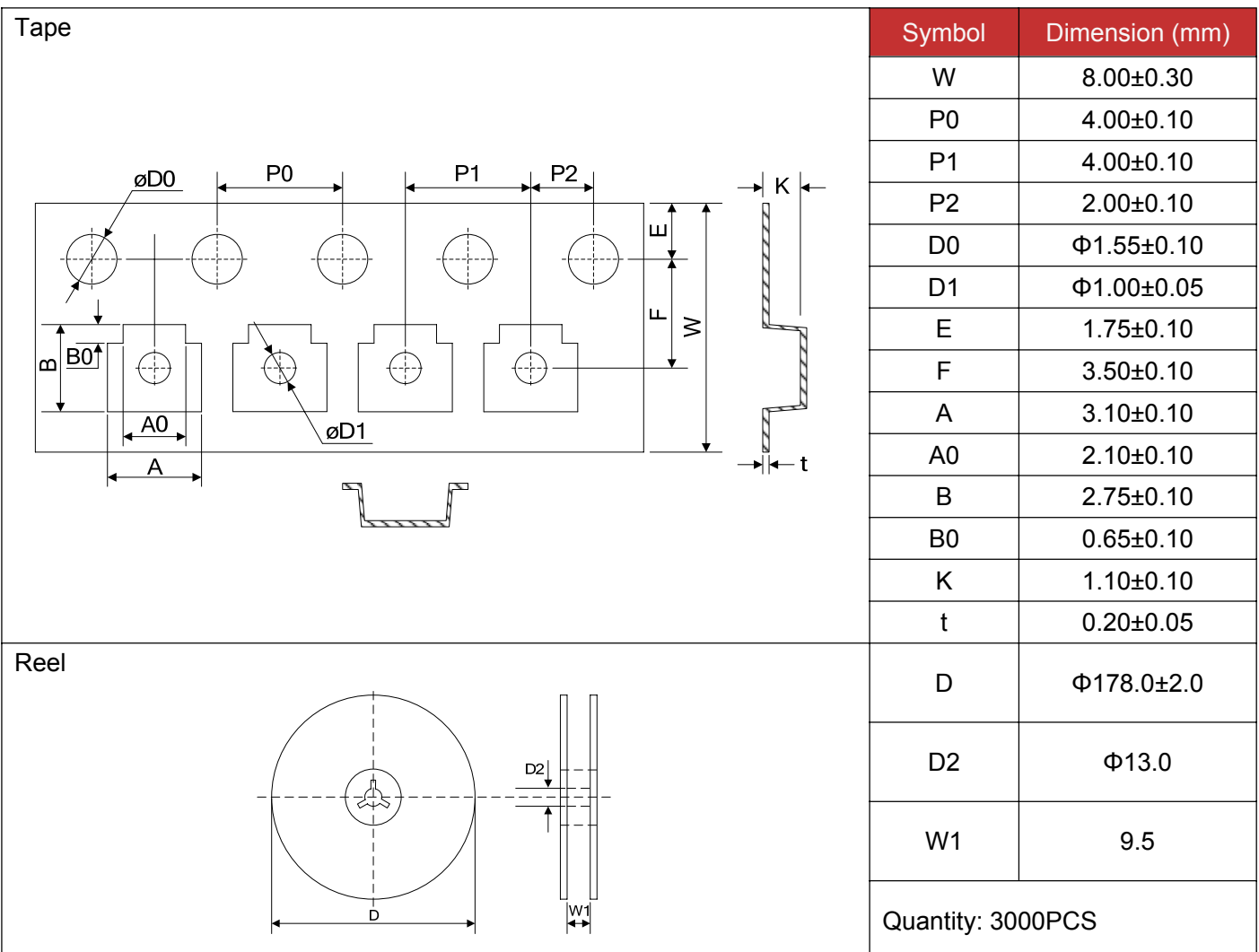
Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOT-23)



Packaging



<p>Label</p>		<p>Note: E18 is special code for customer's requirement.</p>
<p>Box</p>		<p>180mm*180mm*68mm</p>